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DECLARATION - USA PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed  
and for which a patent is sought on the invention entitled WAFER BACK

SURFACE TREATING METHOD AND DICING SHEET ADHERING APPARATUS ;  
the specification of which is attached hereto;

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)

Priority  
Claimed

No.: **2003-152344**

Country: **Japan**

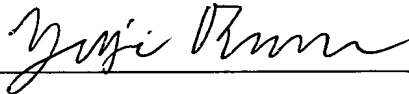
Date Filed: **5/29/03**

**Yes**

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

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Full name of first inventor: **Yuji OKAWA**

Inventor's signature \_\_\_\_\_



Date March 12, 2004

Residence: **1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan**

Citizenship: **Japan**

Post Office Address: **Same as above**

Send Correspondence To: **Daniel E. Altman**  
**KNOBBE, MARTENS, OLSON & BEAR, LLP**

**Customer No. 20,995**

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Yuji OKAWA	)
			)
App. No.	:	Unknown	)
			)
Filed	:	Herewith	)
			)
For	:	WAFER BACK SURFACE	)
		TREATING METHOD AND	)
		DICING SHEET ADHERING	)
		APPARATUS	)
			)
Examiner	:	Unknown	)
			)

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ESTABLISHMENT OF RIGHT OF ASSIGNEE TO TAKE ACTION  
AND  
REVOCATION AND POWER OF ATTORNEY

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

The undersigned is empowered to act on behalf of the assignee below (the "Assignee"). A true copy of the original Assignment of the above-captioned application from the inventor(s) to the Assignee is attached hereto. This Assignment represents the entire chain of title of this invention from the Inventor(s) to the Assignee.

I declare that all statements made herein are true, and that all statements made upon information and belief are believed to be true, and further, that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001, and that willful, false statements may jeopardize the validity of the application, or any patent issuing thereon.

The undersigned hereby revokes any previous powers of attorney in the subject application, and hereby appoints the registrants of Knobbe, Martens, Olson & Bear, LLP, 2040 Main Street, Fourteenth Floor, Irvine, California 92614, Telephone

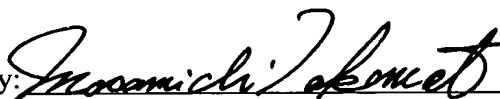
App. No. :  
Filed :

(949) 760-0404, **Customer No. 20,995**, as its attorneys with full power of substitution and revocation to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected herewith. This appointment is to be to the exclusion of the inventor(s) and his attorney(s) in accordance with the provisions of 37 C.F.R. § 3.71.

Please use **Customer No. 20,995** for all communications.

Nitto Denko Corporation

Dated: March 12, 2004

By:   
Masamichi TAKEMOTO

Title: President

Address: 1-1-2, Shimohozumi, Ibaraki-shi, Osaka  
567-8680 Japan

Application No.:  
Filing Date:

PATENT

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**ASSIGNMENT**

WHEREAS, I, Yuji OKAWA, a Japanese citizen, residing at 1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan, have invented certain new and useful improvements in a WAFER BACK SURFACE

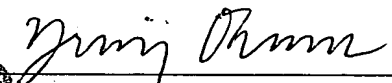
TREATING METHOD AND DICING SHEET ADHERING APPARATUS;  
for which I have executed an application for Letters Patent in the United States, even date herewith;

AND WHEREAS, Nitto Denko Corporation (hereinafter "ASSIGNEE"), a Japanese Corporation, with its principal place of business at 1-1-2, Shimohozumi, Ibaraki-shi, Osaka 567-8680 Japan, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 12th day of March, 2004

  
Yuji OKAWA